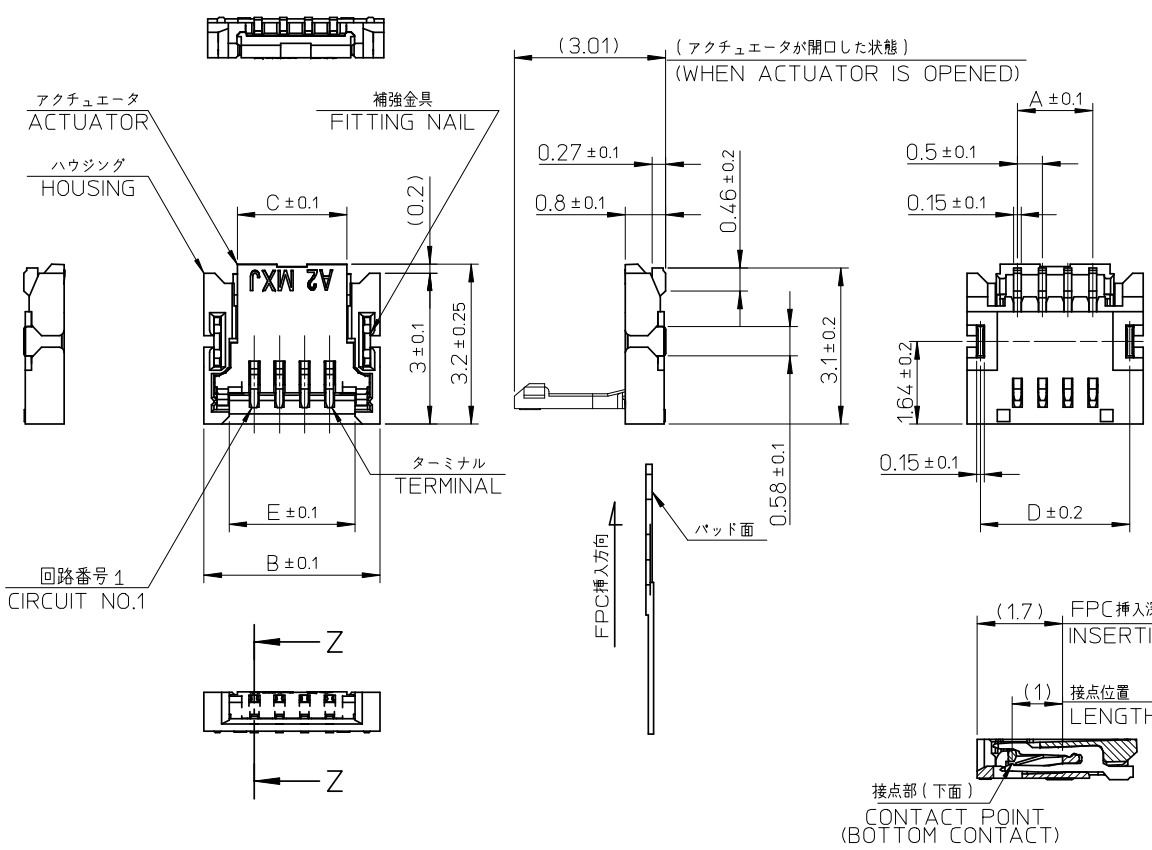


注記  
NOTES:

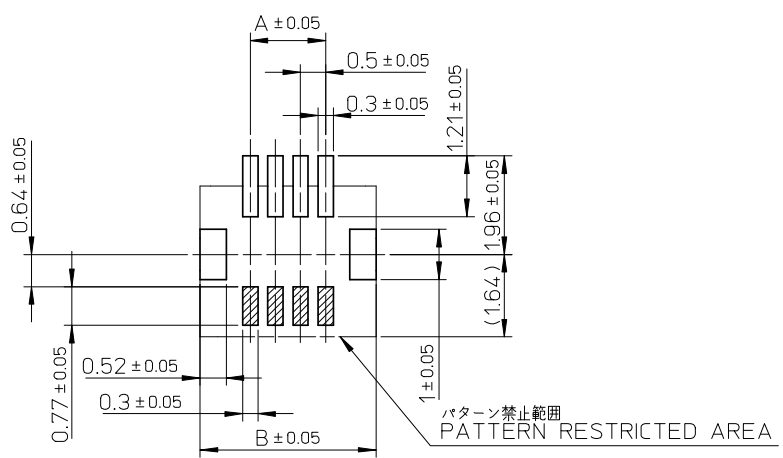
- 材質  
MATERIAL  
ハウジング: ポリアミド46、ガラス充填、UL94HB 塩素系、臭素系難燃材 非使用  
HOUSING: PA46, GLASS FILLED, UL94HB  
CHLORINATED FLAME RETARDANTS FREE/  
BROMINATED FLAME RETARDANTS FREE.  
アクチュエーター: ポリアミド46、ガラス充填、UL94HB 塩素系、臭素系難燃材 非使用  
ACTUATOR: PA46, GLASS FILLED, UL94HB  
CHLORINATED FLAME RETARDANTS FREE/  
BROMINATED FLAME RETARDANTS FREE.  
ターミナル: 銅合金 (t=0.15)  
TERMINAL: COPPER ALLOY (t=0.15)  
補強金具: 銅合金 (t=0.15)  
NAIL: COPPER ALLOY (t=0.15)
- めっき仕様  
PLATING  
ターミナル: 部分金メッキ  
接点部 0.1マイクロメートル以上  
半田付け部 0.05マイクロメートル以上  
TERMINAL: SEPARATED GOLD PLATING  
CONTACT AREA 0.1 MICROMETER MINIMUM.  
SOLDER TAIL AREA 0.05 MICROMETER MINIMUM.  
下地 ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.  
補強金具: 錫メッキ 1.0マイクロメートル以上  
NAIL: TIN PLATING 1.0 MICROMETER MINIMUM.  
下地 ニッケルメッキ 1.0マイクロメートル以上  
UNDER PLATING; NICKEL PLATING 1.0 MICROMETER MINIMUM.
- 平坦度は、0.1mm以下とする。  
TAILS AND NAILS COPLANARITY TO BE 0.1mm MAXIMUM.



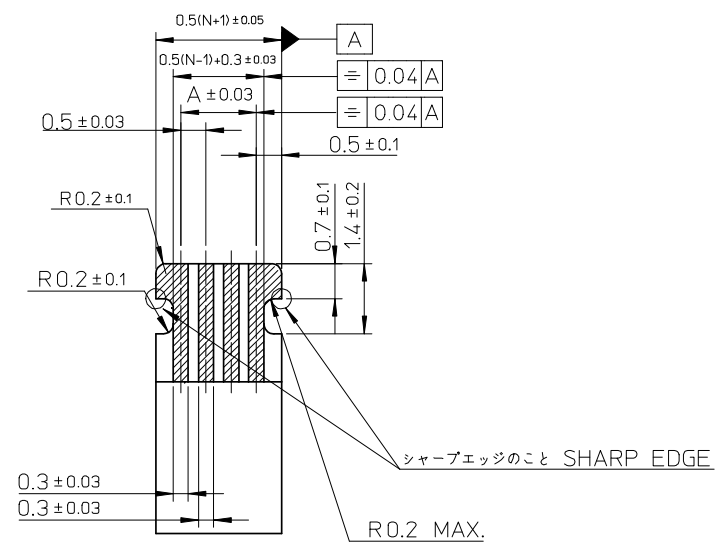
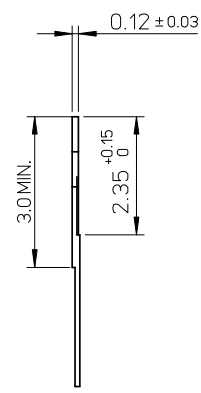
SECTION Z-Z (ACTUATOR CLOSED)

2.5	2.97	2.18	3.5	1.5	503043-0401	503043-0409	4
E	D	C	B	A	エンボス梱包品 製品番号		極数(N) 回路数(N)
EMBOSSED PACKAGING MATERIAL NO.							

REVISED EC NO: J2009-0418 DRWN: ASUZUKI 2008/08/19 CHKD: HMATSUMOTO 2008/08/19 APPR: NUKITA 2008/08/20	DESCRIPTION REV	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY		SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION	
		10 UNDER	±0.2	DRAWN BY Y. AOYAGI	DATE 2008/02/26	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY			
		10 OVER 30 UNDER	±0.25	CHECKED BY E. SATO	DATE 2008/02/26	MOLEX INCORPORATED			
		30 OVER	±0.3	APPROVED BY N. UKITA	DATE 2008/02/26	DOCUMENT NO. SD-503043-001			
DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS		SEE TABLE		SHEET NO. 1 OF 2					
THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION									



推奨基板寸法  
RECOMMENDED P.C. BOARD PATTERN LAYOUT



推奨FPC寸法  
RECOMMENDED FPC PATTERN LAYOUT

FPCについて：  
抜き方向は、導体側から補強板側を推奨します。  
補強フィルム材質は、ポリイミドを推奨します。  
接着剤は、熱硬化接着剤を推奨します。  
尚、接着剤の接点部への付着は、導通不良の原因となりますので染み出しが無いよう、お願いします。

ABOUT FPC：  
RECOMMENDED PUNCHER DIRECTION：  
FROM CONDUCTOR SIDE TO STIFFNER FILM SIDE.  
RECOMMENDED MATERIAL  
STIFFNER FILM : POLYIMIDE  
BONDING AGENT : THERMOSETTING AGENT  
PLEASE PUT APPROPRIATE AMOUNT OF ADHESIVE MAY CAUSE  
THE DEFECT IN ELECTRICAL CONTINUITY.

REVISED EC NO: J2009-0418 DRWN:ASUZUKI01 2008/08/19 CHKD:HMATSUMOTO 2008/08/19 APPR:NUKITA 2008/08/20	GENERAL TOLERANCES (UNLESS SPECIFIED)		DIMENSION STYLE MM ONLY	SCALE 10:1	DESIGN UNITS METRIC	THIRD ANGLE PROJECTION
	10 UNDER	± 0.2	DRAWN BY Y. AOYAGI	DATE 2008/02/26	TITLE 0.5 FPC CONN BACK FLIP HGT=0.8 HSG ASSY	
	10 OVER 30 UNDER	± 0.25	CHECKED BY E. SATO	DATE 2008/02/26	MOLEX INCORPORATED	
	30 OVER	± 0.3	APPROVED BY N. UKITA	DATE 2008/02/26	DOCUMENT NO. SD-503043-001	SHEET NO. 2 OF 2
A	DESCRIPTION ANGULAR ±1 ° DRAFT WHERE APPLICABLE MUST REMAIN WITHIN DIMENSIONS	SEE SHEET 1	THIS DRAWING CONTAINS INFORMATION THAT IS PROPRIETARY TO MOLEX INCORPORATED AND SHOULD NOT BE USED WITHOUT WRITTEN PERMISSION			